

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



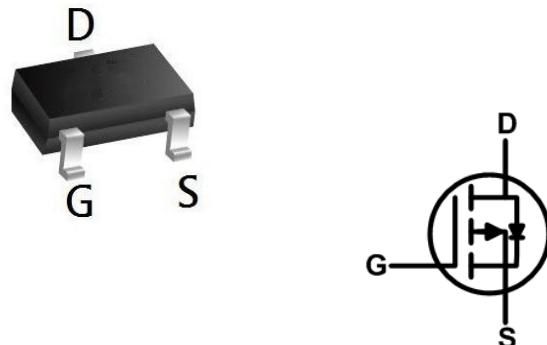
BVDSS	RDS(on)	ID
-100V	180mΩ	-3A

Description

The XXW3P10L is the high cell density trenched P-ch MOSFETs, which provides excellent RDS(on) and efficiency for most of the small power switching and load switch applications.

The XXW3P10L meet the RoHS and Green Product requirement with full function reliability approved.

TO252 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-3	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-1.2	A
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-0.75	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-0.6	A
I _{DM}	Pulsed Drain Current ²	-6	A
EAS	Single Pulse Avalanche Energy ³	14.5	mJ
I _{AS}	Avalanche Current	-4.5	A
P _D @T _C =25°C	Total Power Dissipation ⁴	10	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	72	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	8	°C/W

P-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

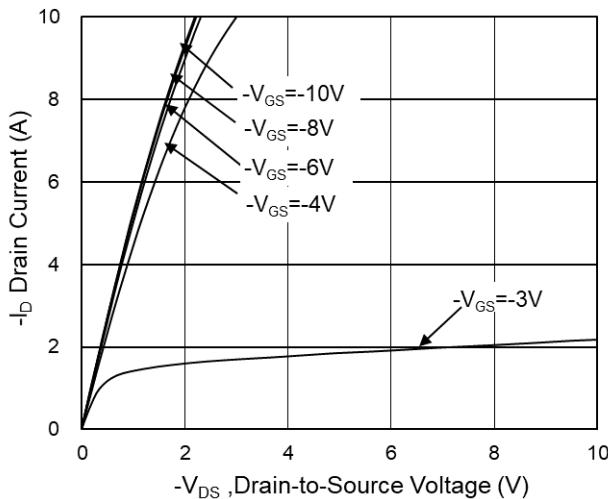
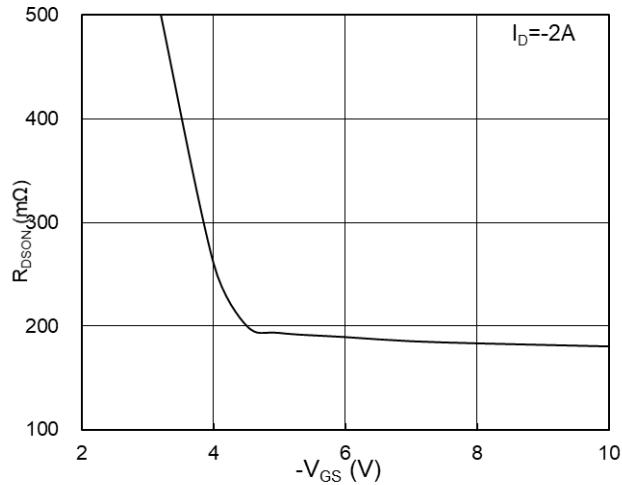
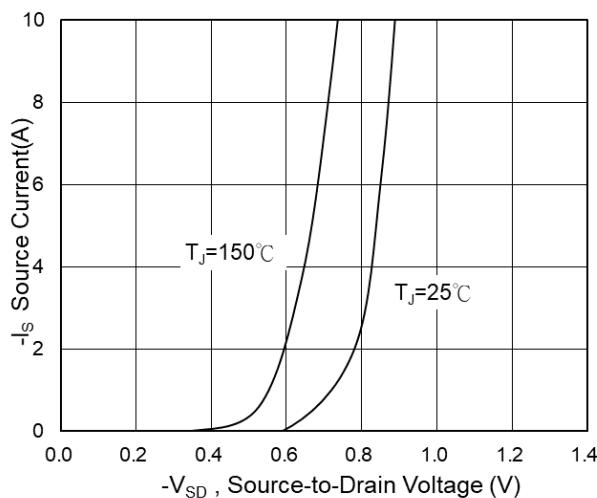
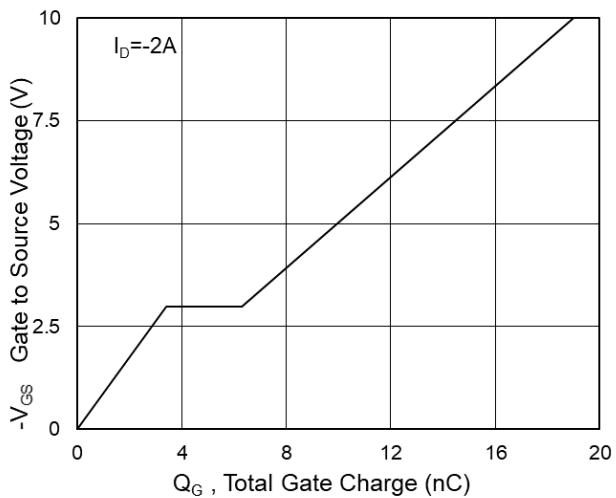
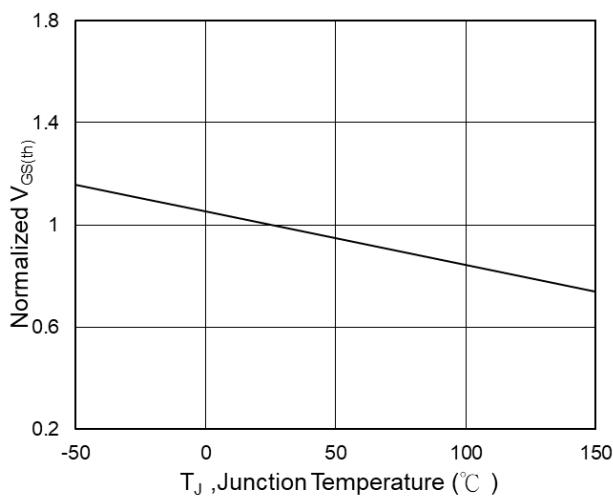
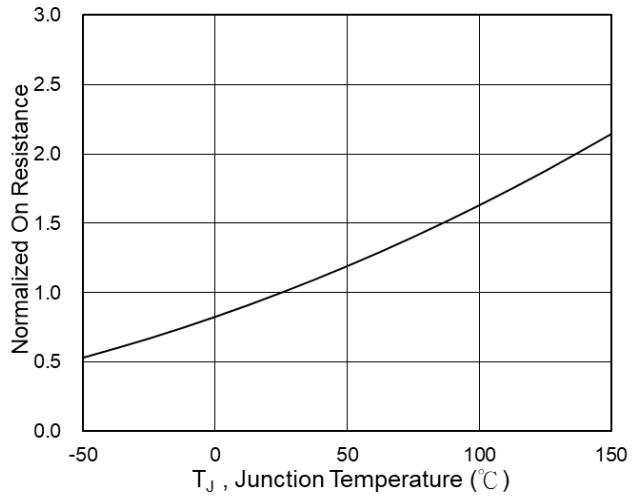
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=-250\mu\text{A}$	-100	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=-10\text{V}$, $\text{I}_D=-3\text{A}$	---	180	220	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_D=-2\text{A}$	---	210	255	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=-250\mu\text{A}$	-1.2	---	-2.5	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^{\circ}\text{C}$	---	---	-1	uA
		$\text{V}_{\text{DS}}=-80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=85^{\circ}\text{C}$	---	---	-30	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	13	---	Ω
Q_g	Total Gate Charge (-10V)	$\text{V}_{\text{DS}}=-50\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $\text{I}_D=-2\text{A}$	---	19	---	nC
Q_{gs}	Gate-Source Charge		---	3.4	---	
Q_{gd}	Gate-Drain Charge		---	2.9	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=-30\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $\text{R}_g=3.3\Omega$, $\text{I}_D=-1\text{A}$	---	9	---	ns
T_r	Rise Time		---	6	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	39	---	
T_f	Fall Time		---	33	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=-30\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1228	---	pF
C_{oss}	Output Capacitance		---	41	---	
C_{rss}	Reverse Transfer Capacitance		---	29	---	

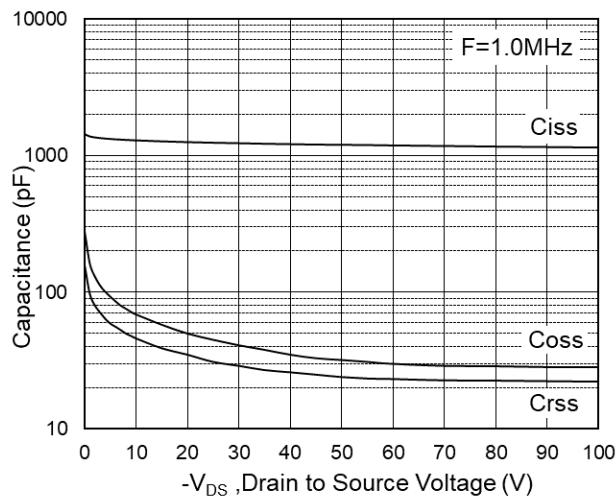
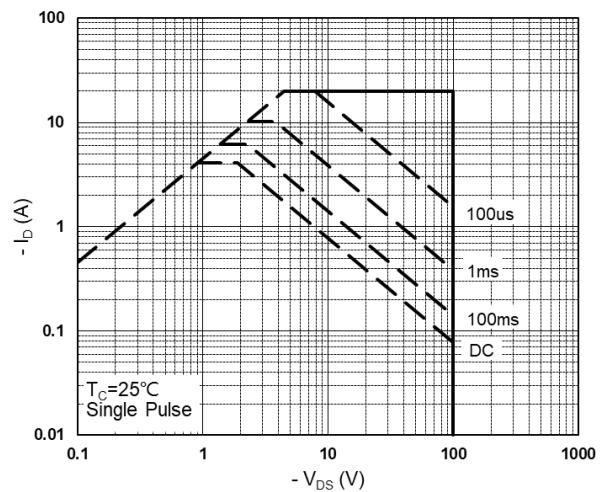
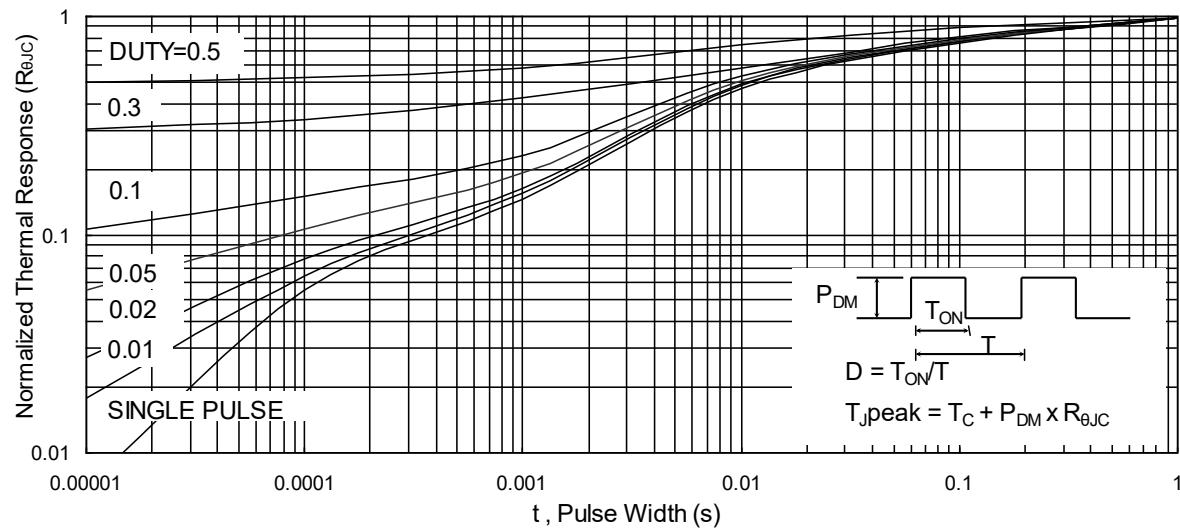
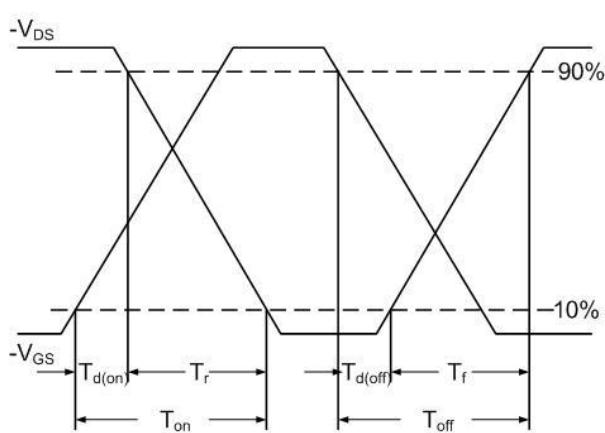
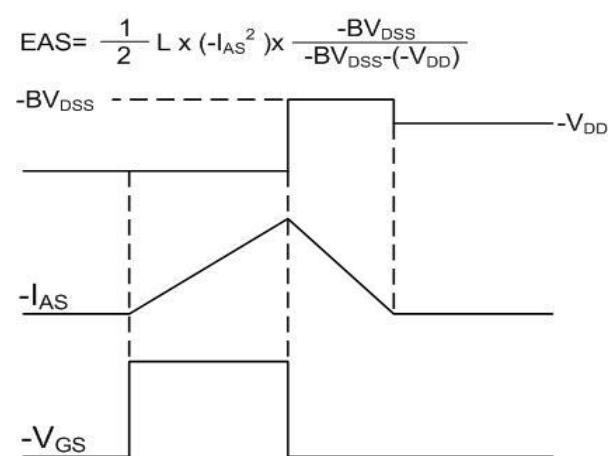
Diode Characteristics

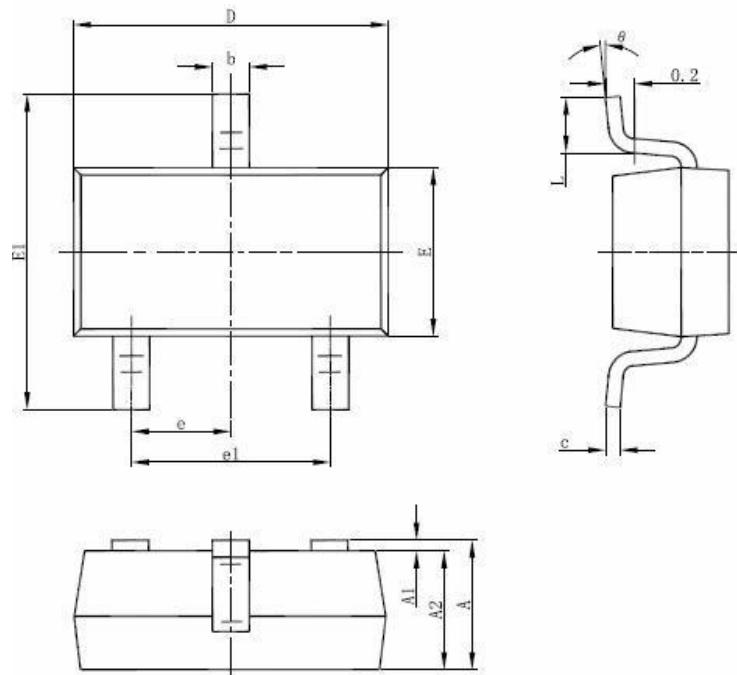
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	3	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=-1\text{A}$, $\text{T}_J=25^{\circ}\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=-25\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $L=0.5\text{mH}$, $\text{I}_{\text{AS}}=-14\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Channel Typical Characteristics

Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs G-S Voltage

Fig.3 Source Drain Forward Characteristics

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs T_J

Fig.6 Normalized $R_{DS(on)}$ vs T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Waveform

SOT-23-3L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°